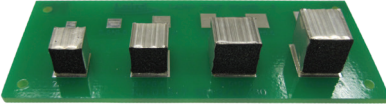


High Temp SMD Grounding Contacts

Metallized Film-over-Silicone Foam



SMD METALLIZED FILM-OVER-SILICONE FOAM GROUNDING CONTACT

Laird's High Temperature SMD (Surface Mount Device) Grounding Contact is a Silicone foam cored contact with a metallized polyimide film outer covering. It is used for circuit grounding of SMT (Surface Mount Technology) devices. These contacts are designed to be solder reflow compatible, and are suitable for automatic processing.

FEATURES

- Sn / Cu Plated PI Film outer layer
- Silicone Foam Core
- High Temp SMD contacts are RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Reflow tunnel compatible to 260° C
- Patent Pending
- UL94 V1 Flammability Rating

MARKETS

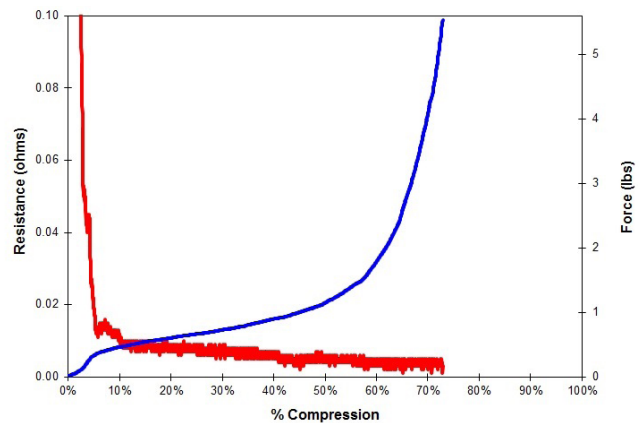
- Automotive
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers and tablets
- Networking equipment
- Desktop computers

Item	Unit	Value	Test Method
Z-Axis Resistance			Laird Internal
Before Reflow	Ω	<0.06	
After Reflow	Ω	<0.10	
Flammability		PASS	UL 94 V1*
Solder Adhesion Strength (Contact to PCB)	kgf	>0.8	Laird Internal
Hardness (Shore A)	durometer	<25	ASTM D 2240
Compression Set	%	<20	ASTM D3574 (125°C,22 hr)
Recommended Compression	%	15 to 30	
Operation Temperature	°C	-40° to 125°	
Restricted Substances		RoHS Compliant Halogen Free	

* UL file number E170327, UL designation code V1 051

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

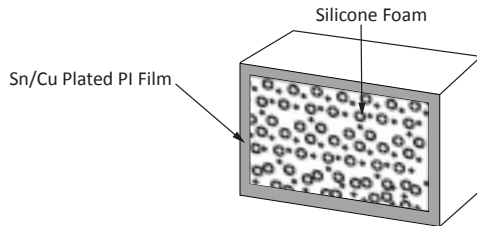
Force/Displacement/Resistance Graph of High Temp Soft SMD Contact W8mm x H6.5mm x L9mm



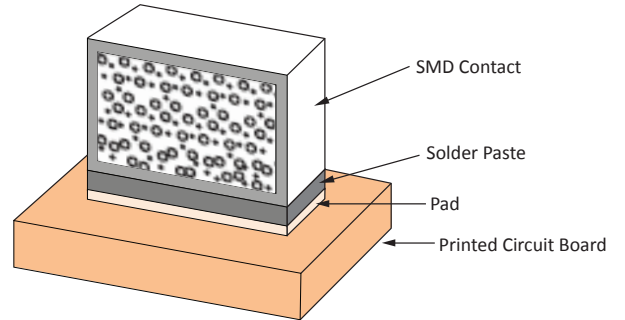
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High Temp SMD Grounding Contacts Metallized Film-over-Silicone Foam

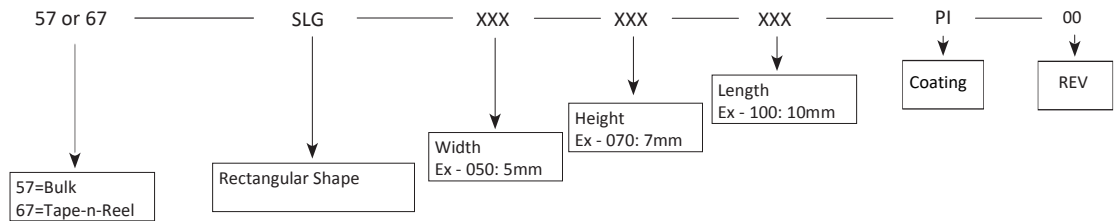
PRODUCT COMPOSITION



PRODUCT APPLICATION



PART NUMBER STRUCTURE



Example: "67-SLM-050-070-100-PI-00" for rectangular shape, 5mm in width, 7mm in height and 10mm length in Tape & Reel.

TYPICAL REFLOW CONDITIONS

	Temperature Profile	Condition	
		Temperature	Time
A	Preheating Stage	Room Temp. -170°C	125 sec.
B	Heating / Soaking Stage	170-217°C	100 sec.
C	Reflow Stage	217-Peak Temp. (~260°C Max)	50 sec.
D	Cooling Stage	Peak Temp. - Room Temp.	>60 sec.

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

EMI-DS-FOF-HIGHTEMP SMD 031419

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